

TOSHIBA Field-Effect Transistor Silicon N-Channel MOS Type

# SSM6K210FE

- High-Speed Switching Applications
- Power Management Switch Applications

- 4.0-V drive
- Low ON-resistance:  $R_{on} = 371 \text{ m}\Omega$  (max) (@ $V_{GS} = 4.0 \text{ V}$ ),  
 $R_{on} = 228 \text{ m}\Omega$  (max) (@ $V_{GS} = 10 \text{ V}$ )

### Absolute Maximum Ratings ( $T_a = 25^\circ\text{C}$ )

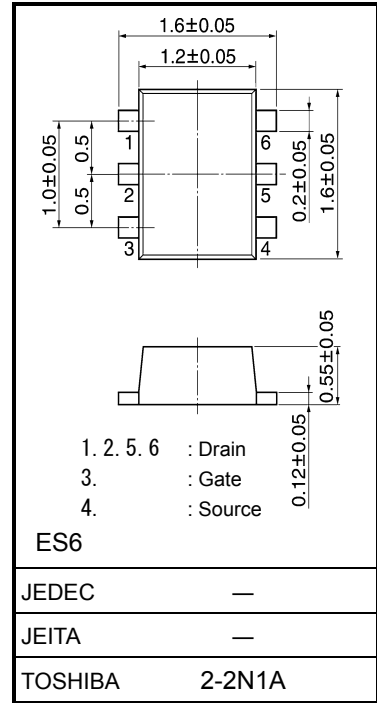
Characteristic		Symbol	Rating	Unit
Drain-source voltage		$V_{DSS}$	30	V
Gate-source voltage		$V_{GSS}$	$\pm 20$	V
Drain current	DC	$I_D$	1.4	A
	Pulse	$I_{DP}$	2.8	
Drain power dissipation		$P_D$ (Note1)	500	mW
Channel temperature		$T_{ch}$	150	$^\circ\text{C}$
Storage temperature		$T_{stg}$	-55 to 150	$^\circ\text{C}$

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

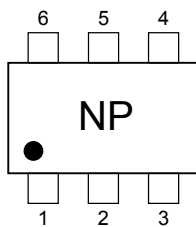
Note 1: Mounted on an FR4 board  
(25.4 mm × 25.4 mm × 1.6 mm, Cu Pad: 645 mm<sup>2</sup>)

Unit: mm

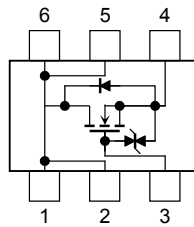


Weight: 3mg (typ.)

### Marking



### Equivalent Circuit (top view)



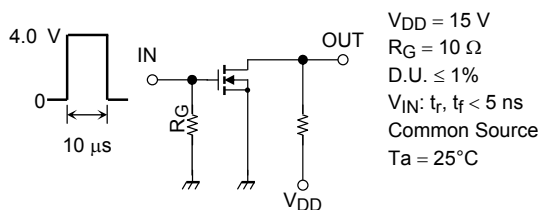
## Electrical Characteristics (Ta = 25°C)

Characteristic	Symbol	Test Condition	Min	Typ.	Max	Unit	
Drain-source breakdown voltage	$V_{(BR)DSS}$	$I_D = 1 \text{ mA}, V_{GS} = 0 \text{ V}$	30	—	—	V	
Drain cutoff current	$I_{DSS}$	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$	—	—	1	$\mu\text{A}$	
Gate leakage current	$I_{GSS}$	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$	—	—	$\pm 1$	$\mu\text{A}$	
Gate threshold voltage	$V_{th}$	$V_{DS} = 5 \text{ V}, I_D = 1 \text{ mA}$	1.1	—	2.6	V	
Forward transfer admittance	$ Y_{fs} $	$V_{DS} = 5 \text{ V}, I_D = 0.6 \text{ A}$ (Note 2)	0.73	1.45	—	S	
Drain-source ON-resistance	$R_{DS(ON)}$	$I_D = 0.6 \text{ A}, V_{GS} = 10 \text{ V}$ (Note 2)	—	171	228	m $\Omega$	
		$I_D = 0.6 \text{ A}, V_{GS} = 4.0 \text{ V}$ (Note 2)	—	271	371		
Input capacitance	$C_{iss}$	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	—	57	—	pF	
Output capacitance	$C_{oss}$		—	33	—		
Reverse transfer capacitance	$C_{rss}$		—	12	—		
Total Gate Charge	$Q_g$	$V_{DS} = 15 \text{ V}, I_D = 1.5 \text{ A}$ $V_{GS} = 10 \text{ V}$	—	2.8	—	nC	
Gate-Source Charge	$Q_{gs}$		—	1.6	—		
Gate-Drain Charge	$Q_{gd}$		—	1.2	—		
Switching time	Turn-on time	$t_{on}$	$V_{DD} = 15 \text{ V}, I_D = 0.6 \text{ A},$ $V_{GS} = 0 \text{ to } 4.0 \text{ V}, R_G = 10 \Omega$	—	12.0	—	ns
	Turn-off time	$t_{off}$		—	6.9	—	
Drain-source forward voltage	$V_{DSF}$	$I_D = -1.4 \text{ A}, V_{GS} = 0 \text{ V}$ (Note 2)	—	-0.85	-1.2	V	

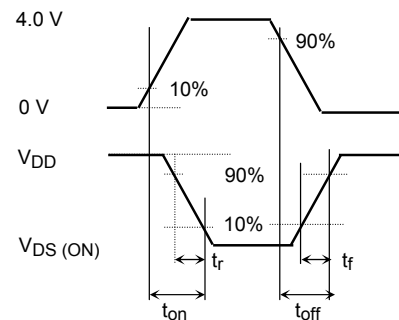
Note 2: Pulse test

## Switching Time Test Circuit

(a) Test Circuit



(b)  $V_{IN}$



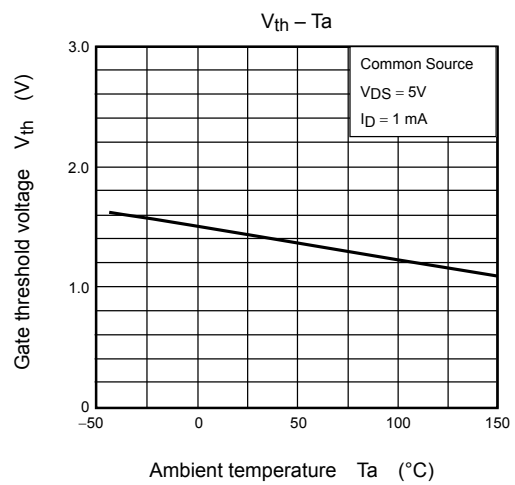
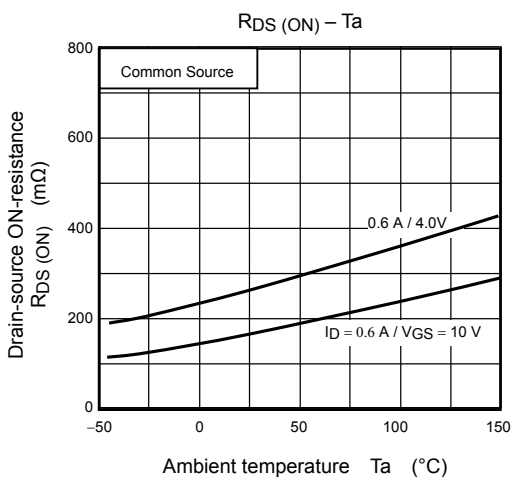
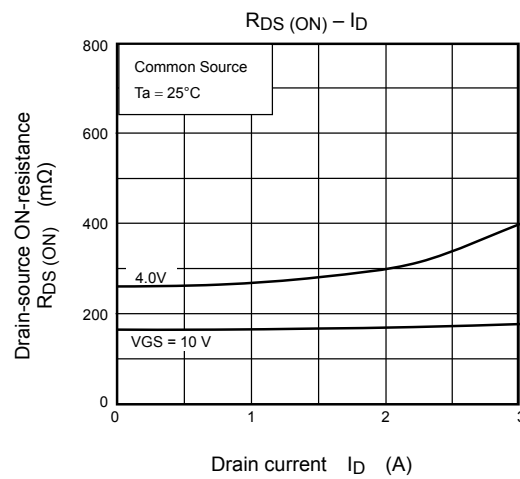
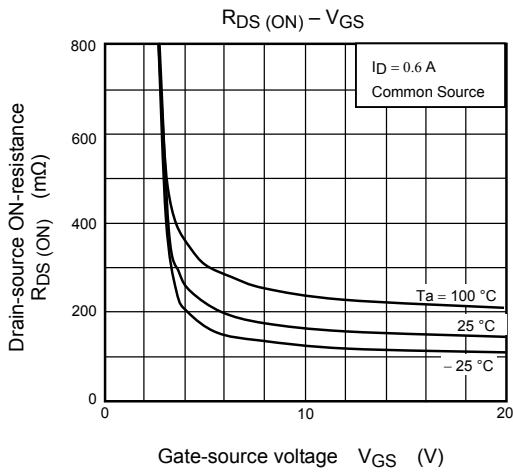
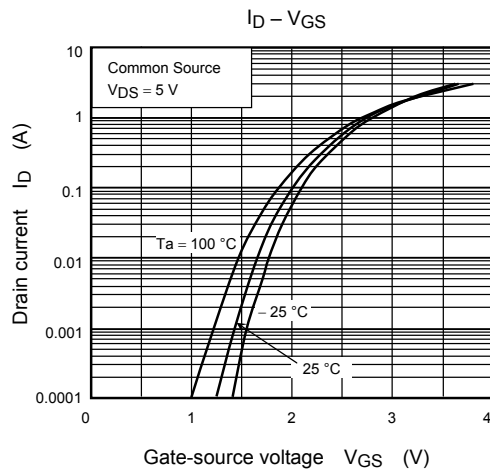
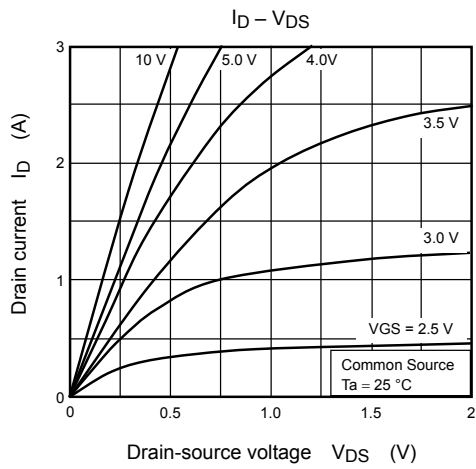
(c)  $V_{OUT}$

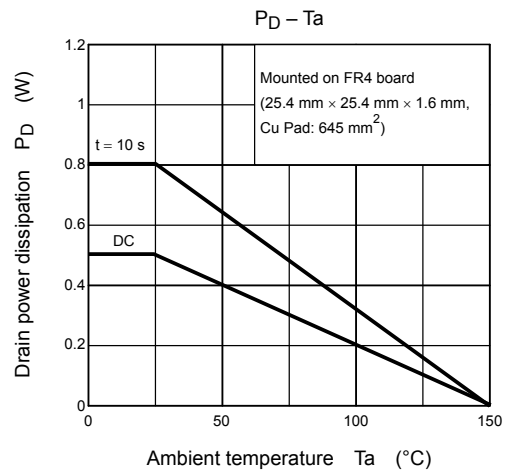
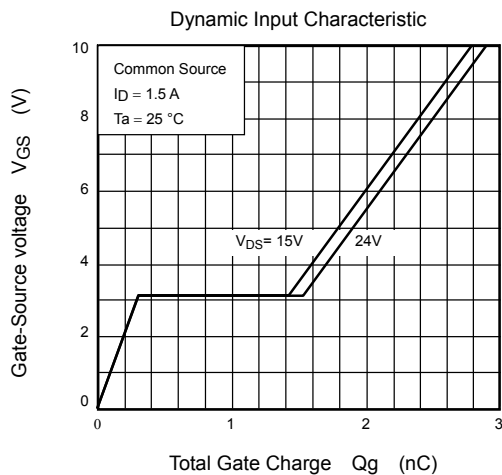
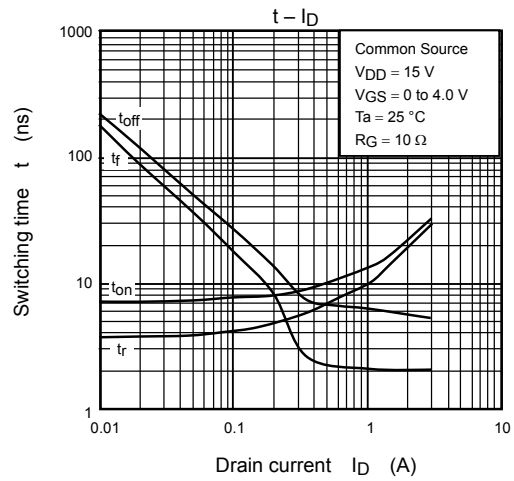
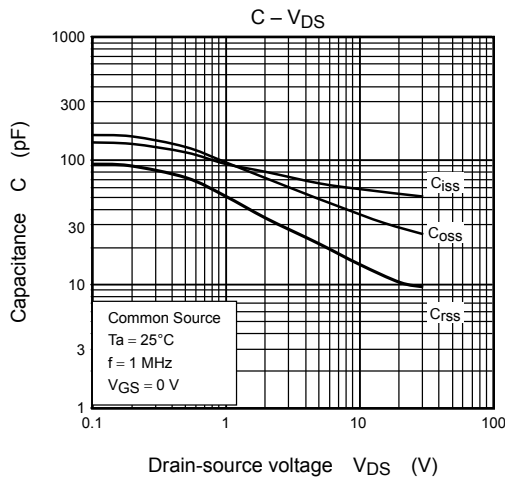
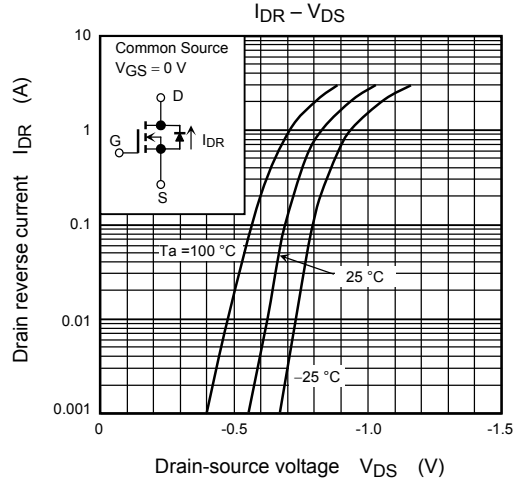
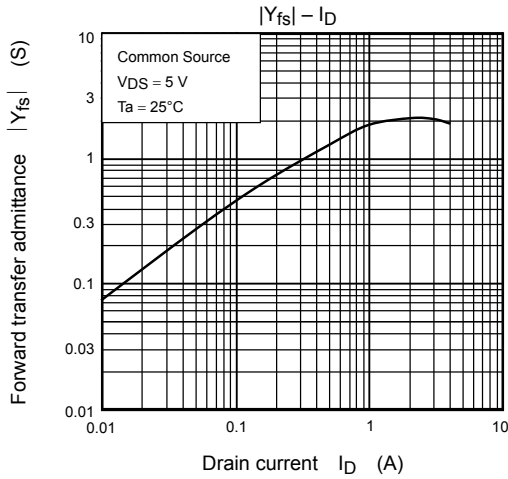
## Notice on Usage

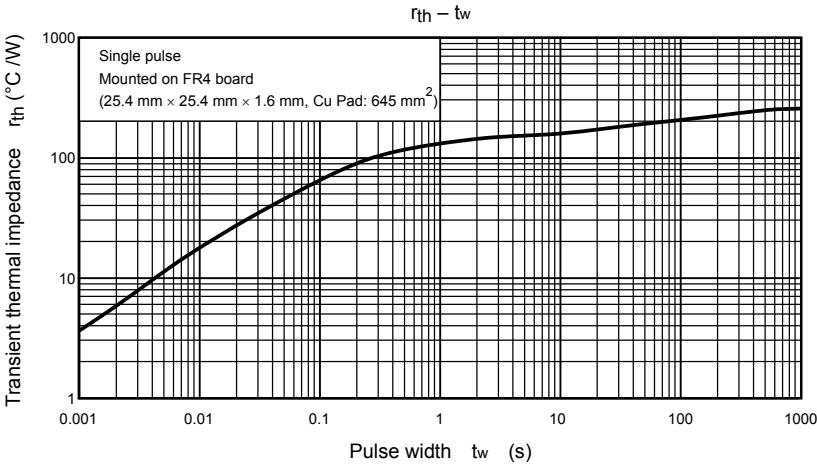
Let  $V_{th}$  be the voltage applied between gate and source that causes the drain current ( $I_D$ ) to be below (1 mA for the SSM6K210FE). Then, for normal switching operation,  $V_{GS(on)}$  must be higher than  $V_{th}$ , and  $V_{GS(off)}$  must be lower than  $V_{th}$ . This relationship can be expressed as:  $V_{GS(off)} < V_{th} < V_{GS(on)}$ . Take this into consideration when using the device.

## Handling Precaution

When handling individual devices that are not yet mounted on a circuit board, make sure that the environment is protected against electrostatic discharge. Operators should wear antistatic clothing, and containers and other objects that come into direct contact with devices should be made of antistatic materials.







**RESTRICTIONS ON PRODUCT USE**

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- TOSHIBA is continually working to improve the quality and reliability of its products. Nevertheless, semiconductor devices in general can malfunction or fail due to their inherent electrical sensitivity and vulnerability to physical stress. It is the responsibility of the buyer, when utilizing TOSHIBA products, to comply with the standards of safety in making a safe design for the entire system, and to avoid situations in which a malfunction or failure of such TOSHIBA products could cause loss of human life, bodily injury or damage to property.  
In developing your designs, please ensure that TOSHIBA products are used within specified operating ranges as set forth in the most recent TOSHIBA products specifications. Also, please keep in mind the precautions and conditions set forth in the "Handling Guide for Semiconductor Devices," or "TOSHIBA Semiconductor Reliability Handbook" etc.
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